### 25-Ω Switch Connection Between Two Ports

- TTL-Compatible Input Levels
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

### description

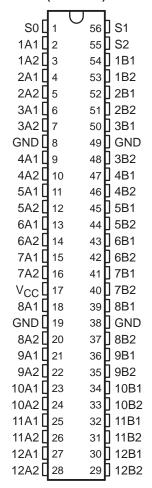
The SN74CBTR16212 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or as a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The device has equivalent  $25-\Omega$  series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

The SN74CBTR16212 is characterized for operation from –40°C to 85°C.

# DGG, DGV, OR DL PACKAGE (TOP VIEW)



### **FUNCTION TABLE**

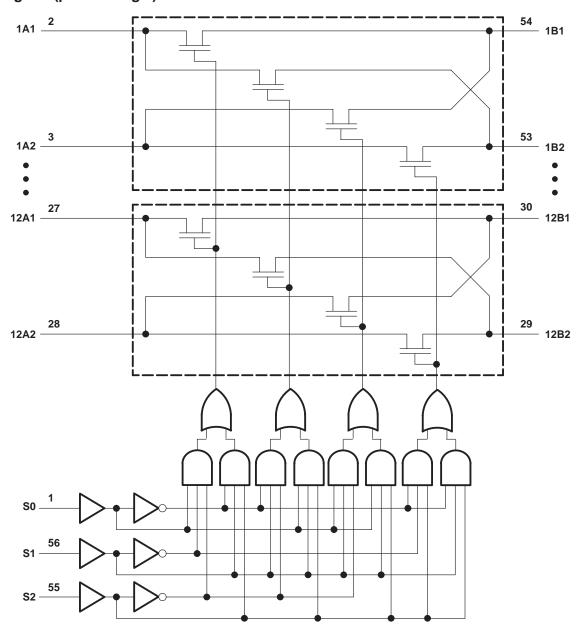
	INPUTS		INPUTS/OUTPUTS		FUNCTION	
S2	S1	S0	A1	A2	FUNCTION	
L	L	L	Z	Z	Disconnect	
L	L	Н	B1 port	Z	A1 port = B1 port	
L	Н	L	B2 port	Z	A1 port = B2 port	
L	Н	Н	Z	B1 port	A2 port = B1 port	
Н	L	L	Z	B2 port	A2 port = B2 port	
Н	L	Н	Z	Z	Disconnect	
н	Н	L	B1 port	B2 port	A1 port = B1 port A2 port = B2 port	
Н	Н	Н	B2 port	B1 port	A1 port = B2 port A2 port = B1 port	



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## logic diagram (positive logic)





### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		-0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)		-0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	): DGG package	64°C/W
	DGV package	48°C/W
	DL package	56°C/W
Storage temperature range, T <sub>stg</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2	V
l <sub>1</sub>		$V_{CC} = 0$ ,	V <sub>I</sub> = 5.5 V				10	μА
		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	
Icc		$V_{CC} = 5.5 \text{ V},$	I <sub>O</sub> = 0,	$V_I = V_{CC}$ or GND			3	μΑ
ΔlCC§	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V <sub>CC</sub> or GND			2.5	mA
Ci	Control inputs	V <sub>I</sub> = 3 V or 0						pF
C <sub>io(OFF)</sub>	)	$V_{O} = 3 \text{ V or } 0,$	S0, S1, or S2 = V <sub>CC</sub>					pF
ron¶		V <sub>CC</sub> = 4.5 V	V <sub>1</sub> = 0	I <sub>I</sub> = 64 mA				
				I <sub>I</sub> = 30 mA				Ω
			V <sub>I</sub> = 2.4 V,	I <sub>I</sub> = 15 mA				

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  (unless otherwise noted),  $T_A = 25^{\circ}C$ .



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

<sup>¶</sup> Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

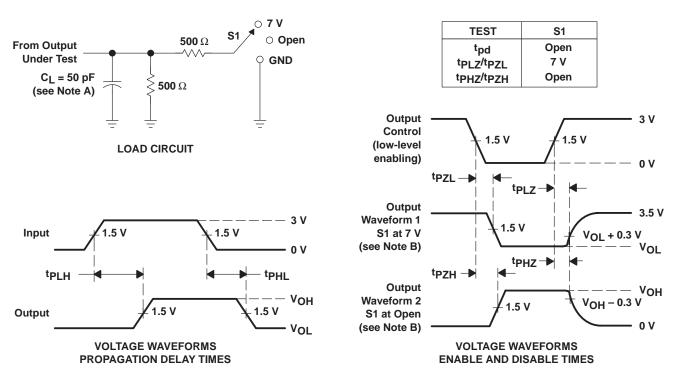
# PRODUCT PREVIEW

switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN MAX	UNIT
t <sub>pd</sub> †	A or B	B or A		ns
<sup>t</sup> pd	S	A or B		ns
<sup>t</sup> en	S	A or B		ns
<sup>t</sup> dis	S	A or B		ns

<sup>†</sup> The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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